



Material Content Data Sheet



Sales Product Name		SPD02N60S5		Issued		1. August 2018		
MA#		MA000851430						
Package		PG-TO252-3-311		Weight*		313.40 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	1.473	0.47	0.47	4699	4699
leadframe	inorganic material	phosphorus	7723-14-0	0.043	0.01		137	
	non noble metal	iron	7439-89-6	0.143	0.05		457	
	non noble metal	copper	7440-50-8	143.098	45.67	45.73	456593	457187
	non noble metal	aluminium	7429-90-5	0.510	0.16	0.16	1629	1629
wire	inorganic material	antimonytrioxide	1309-64-4	2.007	0.64		6403	
encapsulation	plastics	brominated resin	-	2.150	0.69		6860	
	organic material	carbon black	1333-86-4	2.293	0.73		7317	
	plastics	epoxy resin	-	19.350	6.17		61740	
	inorganic material	silicondioxide	60676-86-0	117.531	37.50	45.73	375013	457333
leadfinish	non noble metal	tin	7440-31-5	3.740	1.19	1.19	11934	11934
plating	inorganic material	phosphorus	7723-14-0	0.000	0.00		1	
	non noble metal	nickel	7440-02-0	0.086	0.03	0.03	276	277
solder	non noble metal	tin	7440-31-5	0.036	0.01		113	
	noble metal	silver	7440-22-4	0.044	0.01		142	
	non noble metal	lead	7439-92-1	1.697	0.54	0.56	5416	5671
heatspreader	inorganic material	phosphorus	7723-14-0	0.006	0.00		18	
	non noble metal	iron	7439-89-6	0.019	0.01		61	
	non noble metal	copper	7440-50-8	19.177	6.12	6.13	61191	61270
*deviation	< 10%				Sum in total:	100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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